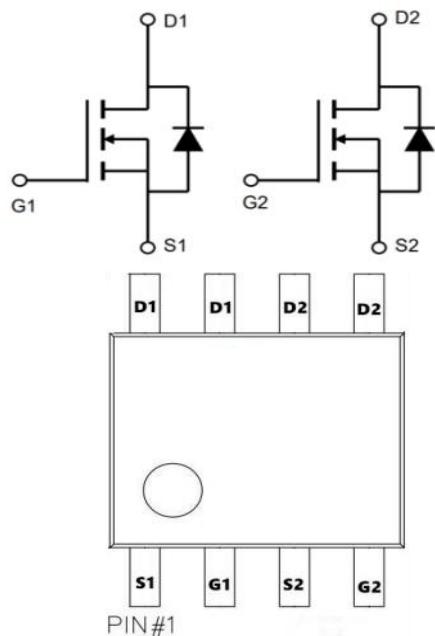


**Description**

The SX20H04S uses advanced trench technology to provide excellent  $R_{DS(ON)}$ , low gate charge and operation with gate voltages as low as 4.5V. This device is suitable for use as a Battery protection or in other Switching application.

**General Features**

$V_{DS} = 40V$   $I_D = 20A$

$R_{DS(ON)} < 10.5m\Omega$  @  $V_{GS}=10V$

**Application**

Battery  
protection Load  
switch  
Uninterruptible power supply

**SOP-8****Absolute Maximum Ratings ( $T_A=25^\circ C$  unless otherwise noted)**

Symbol	Parameter	Rating	Units
$V_{DS}$	Drain-Source Voltage	40	V
$V_{GS}$	Gate-Source Voltage	$\pm 20$	V
$I_D@T_A=25^\circ C$	Continuous Drain Current, $V_{GS} @ 10V$	20	A
$I_D@T_A=70^\circ C$	Continuous Drain Current, $V_{GS} @ 10V$	10.2	A
$IDM$	Pulsed Drain Current <sup>2</sup>	60	A
$EAS$	Single Pulse Avalanche Energy <sup>3</sup>	51	mJ
$I_{AS}$	Avalanche Current	25	A
$PD@T_A=25^\circ C$	Total Power Dissipation <sup>4</sup>	1.5	W
$T_{STG}$	Storage Temperature Range	-55 to 150	°C
$T_J$	Operating Junction Temperature Range	-55 to 150	°C
$R_{\theta JA}$	Thermal Resistance Junction-ambient (Steady State) <sup>1</sup>	85	°C/W
$R_{\theta JC}$	Thermal Resistance Junction-Case <sup>1</sup>	36	°C/W

**N-CH Electrical Characteristics ( $T_A=25^\circ\text{C}$  unless otherwise noted)**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$\text{BV}_{\text{DSS}}$	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}$ , $I_D=250\mu\text{A}$	40	---	---	V
$\Delta \text{BV}_{\text{DSS}}/\Delta T_J$	BVDSS Temperature Coefficient	Reference to $25^\circ\text{C}$ , $I_D=1\text{mA}$	---	0.034	---	$\text{V}/^\circ\text{C}$
$R_{\text{DS}(\text{ON})}$	Static Drain-Source On-Resistance <sup>2</sup>	$V_{\text{GS}}=10\text{V}$ , $I_D=6\text{A}$	---	8.5	10.5	$\text{m}\Omega$
		$V_{\text{GS}}=4.5\text{V}$ , $I_D=3\text{A}$	---	11.0	15	
$V_{\text{GS}(\text{th})}$	Gate Threshold Voltage	$V_{\text{GS}}=V_{\text{DS}}$ , $I_D=250\mu\text{A}$	1.0	---	2.5	V
$\Delta V_{\text{GS}(\text{th})}$	$V_{\text{GS}(\text{th})}$ Temperature Coefficient		---	-5.64	---	$\text{mV}/^\circ\text{C}$
$I_{\text{DS}}$	Drain-Source Leakage Current	$V_{\text{DS}}=32\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $T_J=25^\circ\text{C}$	---	---	1	$\text{uA}$
		$V_{\text{DS}}=32\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $T_J=55^\circ\text{C}$	---	---	5	
$I_{\text{GSS}}$	Gate-Source Leakage Current	$V_{\text{GS}}=\pm 20\text{V}$ , $V_{\text{DS}}=0\text{V}$	---	---	$\pm 100$	nA
$g_{\text{fs}}$	Forward Transconductance	$V_{\text{DS}}=5\text{V}$ , $I_D=6\text{A}$	---	31	---	S
$R_g$	Gate Resistance	$V_{\text{DS}}=0\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $f=1\text{MHz}$	---	2.1	---	$\Omega$
$Q_g$	Total Gate Charge (4.5V)	$V_{\text{DS}}=20\text{V}$ , $V_{\text{GS}}=4.5\text{V}$ , $I_D=6\text{A}$	---	10.7	---	$\text{nC}$
$Q_{\text{gs}}$	Gate-Source Charge		---	3.3	---	
$Q_{\text{gd}}$	Gate-Drain Charge		---	4.2	---	
$T_{\text{d}(\text{on})}$	Turn-On Delay Time	$V_{\text{DD}}=12\text{V}$ , $V_{\text{GS}}=10\text{V}$ , $R_G=3.3\text{k}\Omega$ $I_D=6\text{A}$	---	8.6	---	$\text{ns}$
$T_r$	Rise Time		---	3.4	---	
$T_{\text{d}(\text{off})}$	Turn-Off Delay Time		---	25	---	
$T_f$	Fall Time		---	2.2	---	
$C_{\text{iss}}$	Input Capacitance	$V_{\text{DS}}=15\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $f=1\text{MHz}$	---	1314	---	$\text{pF}$
$C_{\text{oss}}$	Output Capacitance		---	120	---	
$C_{\text{rss}}$	Reverse Transfer Capacitance		---	88	---	
$I_s$	Continuous Source Current <sup>1,5</sup>	$V_G=V_D=0\text{V}$ , Force Current	---	---	7.5	A
$I_{\text{SM}}$	Pulsed Source Current <sup>2,5</sup>		---	---	30	A
$V_{\text{SD}}$	Diode Forward Voltage <sup>2</sup>	$V_{\text{GS}}=0\text{V}$ , $I_S=1\text{A}$ , $T_J=25^\circ\text{C}$	---	---	1.2	V

**Note :**1.The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper.2.The data tested by pulsed , pulse width  $\leq 300\text{us}$  , duty cycle  $\leq 2\%$ 

3.The EAS data shows Max. rating . The test condition is

 $V_{\text{DD}}=25\text{V}$ ,  $V_{\text{GS}}=10\text{V}$ ,  $L=0.1\text{mH}$ ,  $I_{\text{AS}}=25\text{A}$  4 .The power dissipation is limited by  $175^\circ\text{C}$  junction temperature5.The data is theoretically the same as  $I_{\text{D}}$  and  $I_{\text{DM}}$  , in real applications , should be limited by total power dissipation.

## Typical Characteristics

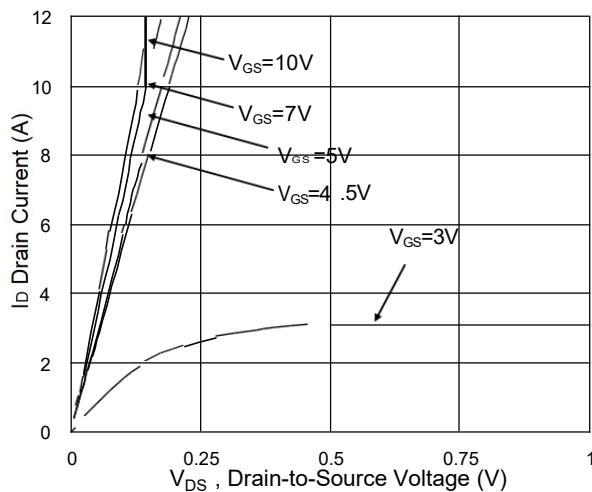


Fig.1 Typical Output Characteristics

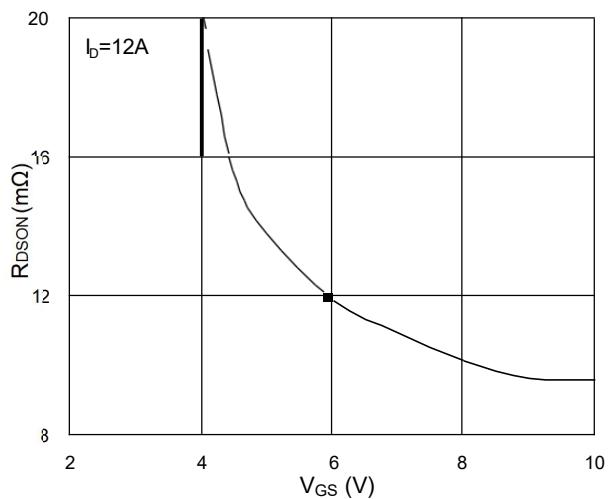


Fig.2 On-Resistance vs. G-S Voltage

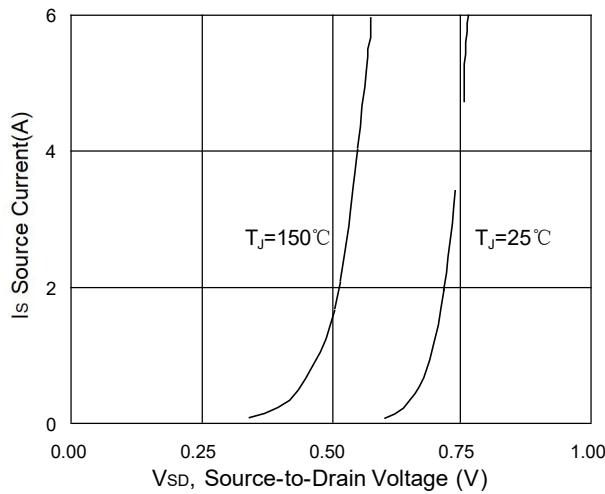


Fig.3 Forward Characteristics of Reverse

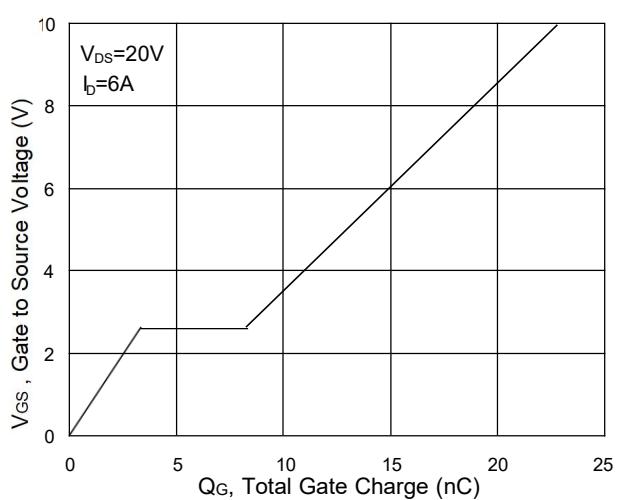


Fig.4 Gate-Charge Characteristics

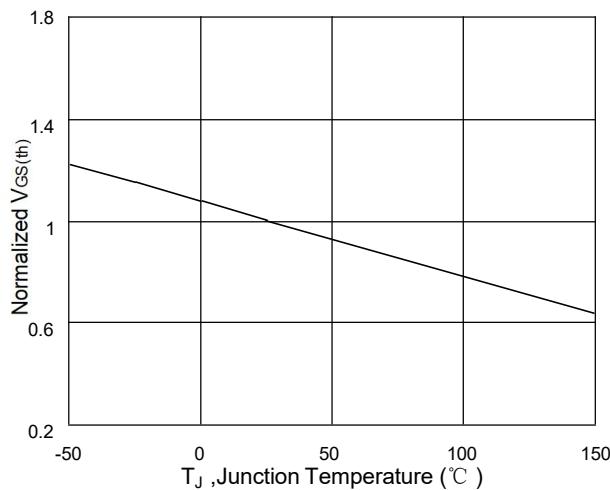


Fig.5 Normalized  $V_{GS(th)}$  vs.  $T_J$

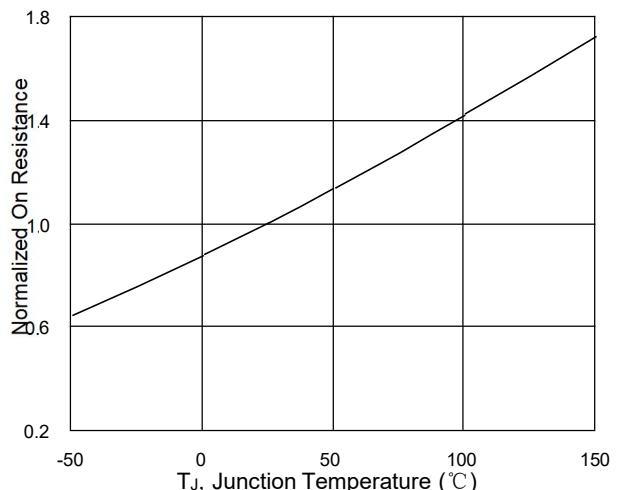


Fig.6 Normalized  $R_{DS(on)}$  vs.  $T_J$

### Typical Characteristics

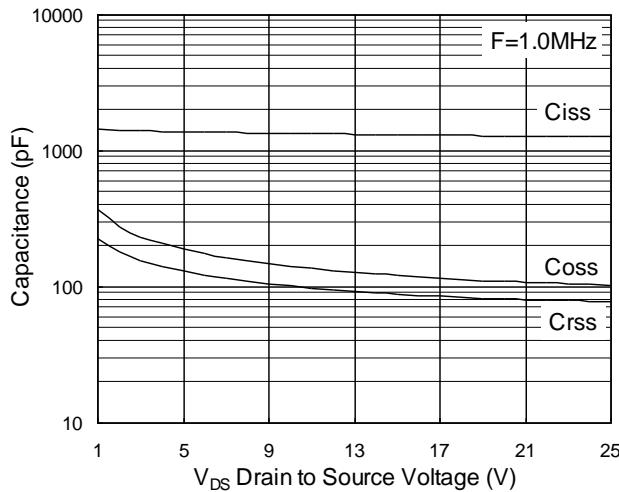


Fig.7 Capacitance

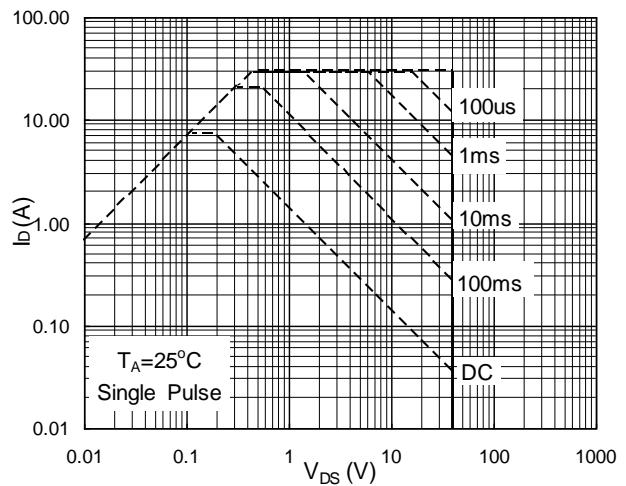


Fig.8 Safe Operating Area

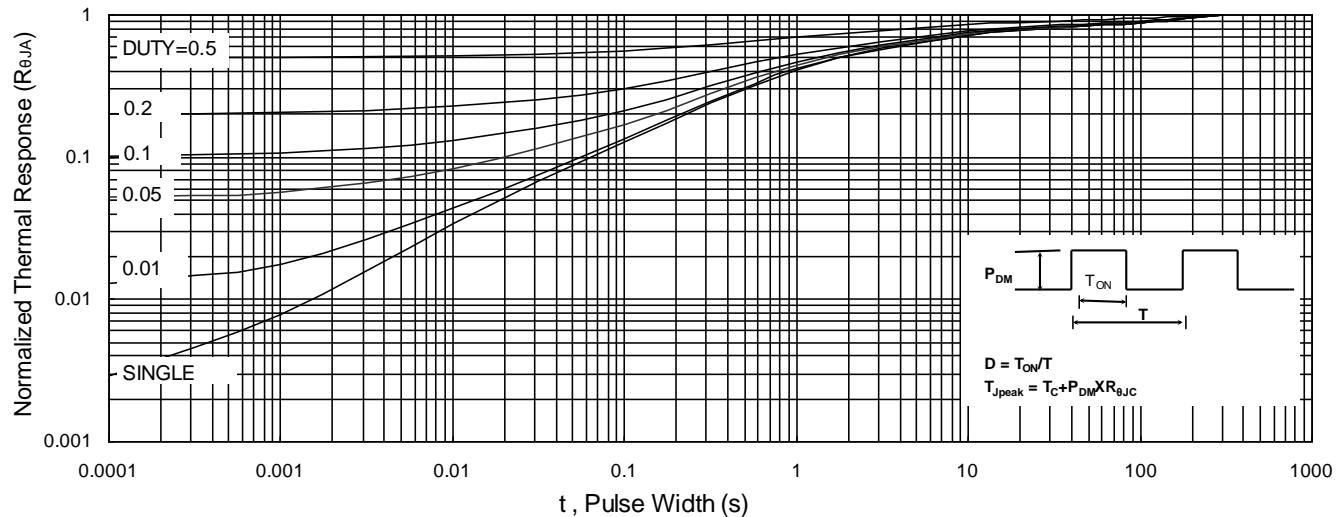


Fig.9 Normalized Maximum Transient Thermal Impedance

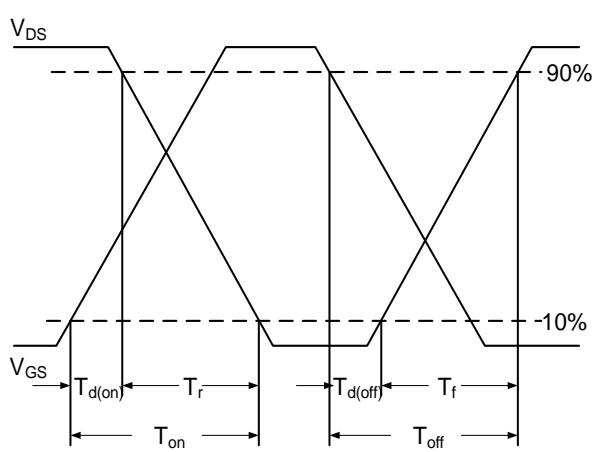


Fig.10 Switching Time Waveform

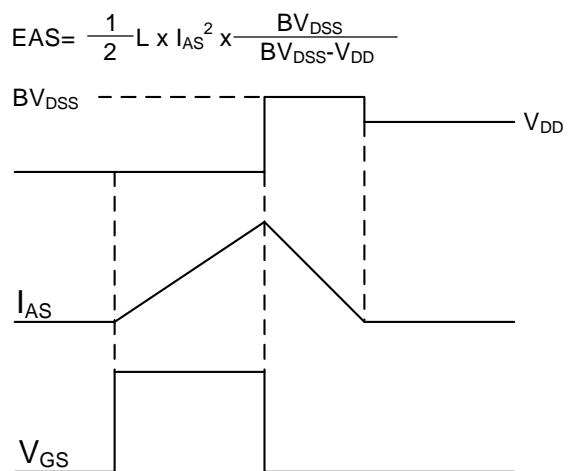
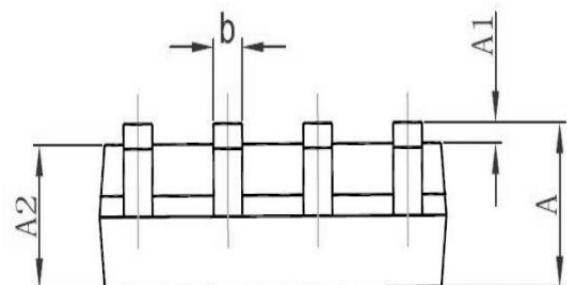
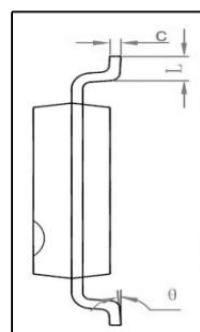
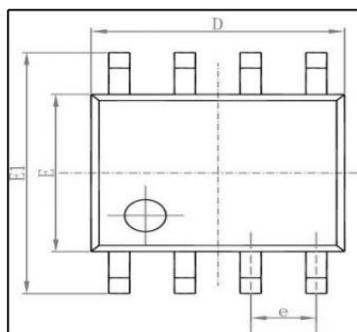
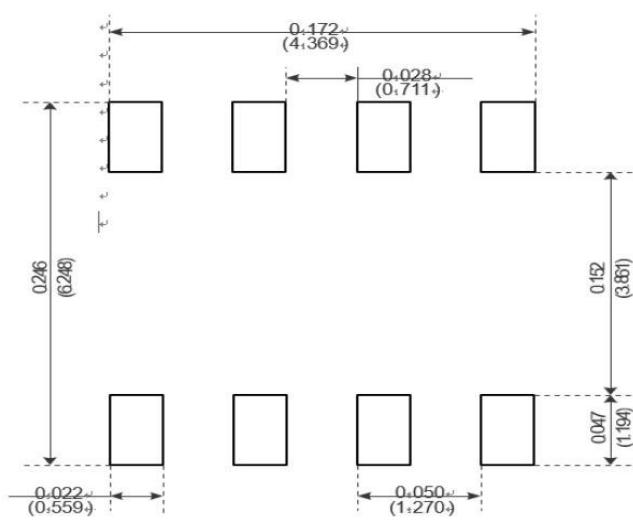


Fig.11 Unclamped Inductive Switching Waveform

**MOSFET Package Mechanical Data-SOP-8**

Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	1.350	1.750	0.053	0.069
A1	0.100	0.250	0.004	0.010
A2	1.350	1.550	0.053	0.061
b	0.330	0.510	0.013	0.020
c	0.170	0.250	0.006	0.010
D	4.700	5.100	0.185	0.200
E	3.800	4.000	0.150	0.157
E1	5.800	6.200	0.228	0.244
e	1.270 (BSC)		0.050 (BSC)	
L	0.400	1.270	0.016	0.050
$\theta$	0°	8°	0°	8°



Recommended Minimum Pads

**Package Marking and Ordering Information**

Product ID	Pack	Marking	Qty(PCS)
TAPING	SOP-8		3000